

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A method of manufacturing a multilayer circuit board, in which a plurality of printed boards are stacked and pressed into a multilayer circuit board, each printed board having a conductor layer on one side of an insulating layer, the method comprising:

stacking the printed boards with a bonding layer being interposed between the printed boards, each printed board having a via hole extending through the insulating substrate to the conductor layer, the via hole being filled with a plated conductor, the plated conductor being formed with a conductive bump extending through the bonding layer so that the conductive bump is connected to the conductor layer of ~~the other~~ another stacked printed board;

stacking an outermost conductor layer made of a copper foil on an insulating layer side of a first outermost printed board with a bonding layer being interposed therebetween; and

pressing a stack so that the printed boards and the outermost conductor layer are bonded together, the first outermost printed board being disposed with the insulating layer side being directed outward.

Claim 2 (previously presented): The method according to claim 1, wherein the stack of printed boards includes a second outermost printed board disposed with a conductor layer side being directed outward, the conductor layer being pressed under a condition where the conductor layer has a uniform thickness all over.

Claim 3 (previously presented): The method according to claim 1, wherein the conductive bump projects from an upper surface of the insulating substrate.

Claim 4 (previously presented): The method according to claim 1, wherein the conductive bump is made from a material with a low melting point.

Claim 5 (previously presented): The method according to claim 1, wherein the plated conductor filling the via hole has an amount determined so that an upper face thereof is lower than the surface of the insulating substrate.